

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT4240017

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DAVID FRANCIS BERDY	01/11/2017
CHANGHAN HOBIE YUN	01/11/2017
NIRANJAN SUNIL MUDAKATTE	01/11/2017
MARIO FRANCISCO VELEZ	01/11/2017
CHENGJIE ZUO	01/11/2017
JONGHAE KIM	01/11/2017
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15239751
CORRESPONDENCE DATA	
Fax Number:	(310)201-5219
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	Qualcomm-USPTO@seyfarth.com
Correspondent Name:	SEYFARTH SHAW LLP
Address Line 1:	2029 CENTURY PARK EAST, SUITE 3500
Address Line 4:	LOS ANGELES, CALIFORNIA 90067
ATTORNEY DOCKET NUMBER:	162923
NAME OF SUBMITTER:	JOSEPH LUTZ
SIGNATURE:	/Joseph Lutz/
DATE SIGNED:	01/24/2017
Total Attachments: 3	

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PATENT

REEL: 041064 FRAME: 0516

ASSIGNMENT

WHEREAS, WE,

4. **Mario Francisco VELEZ**, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of San Diego, California,

5. **Chengjie ZUO**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of San Diego, California,

6. **Jonghae KIM**, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs,

acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that

may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **15/239,751**, filed **August 17, 2016**, Qualcomm Reference No. **162923**, and all provisional applications relating thereto, and all ~~divisional applications, amendment applications, continuation applications, continuation-in-part~~

addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

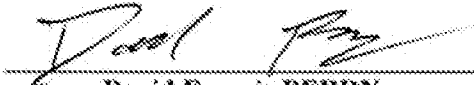
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

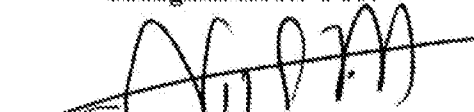
Done at San Diego, CA, on 1/11/17
LOCATION DATE


David Francis BERDY

Done at San Diego, CA, on 1/11/17
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Changhan Hobie YUN

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